

# MECHANICAL CASE OUTLINE

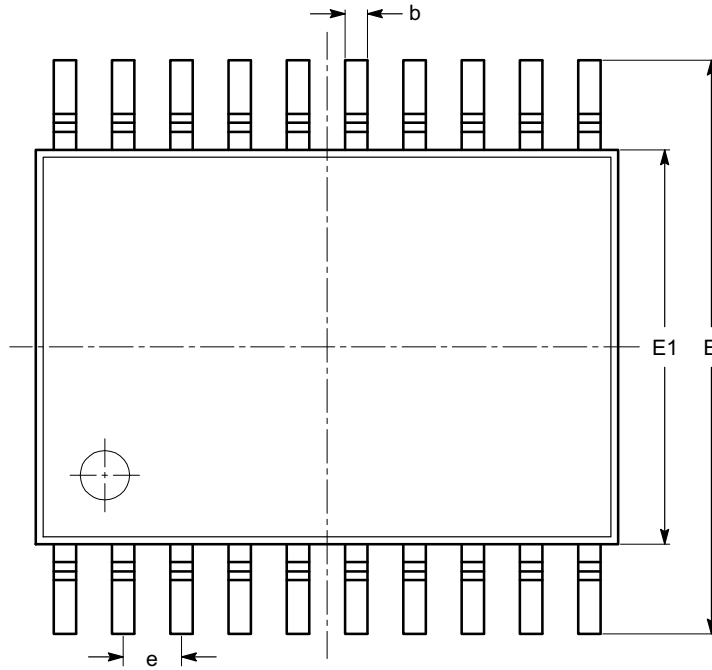
## PACKAGE DIMENSIONS

ON Semiconductor®



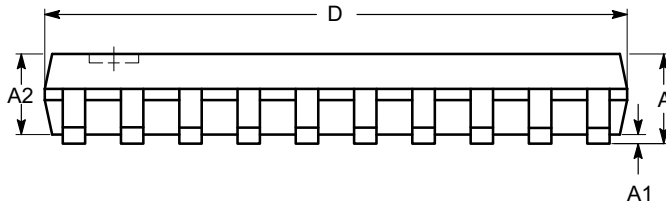
TSSOP20, 4.4x6.5  
CASE 948AQ-01  
ISSUE A

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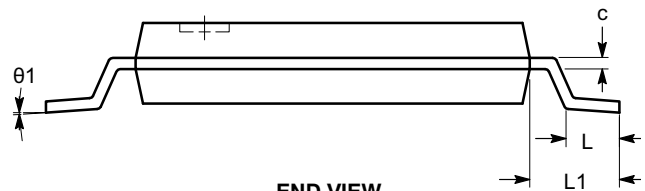


TOP VIEW

SYMBOL	MIN	NOM	MAX
A			1.20
A1	0.05		0.15
A2	0.80		1.05
b	0.19		0.30
c	0.09		0.20
D	6.40	6.50	6.60
E	6.30	6.40	6.50
E1	4.30	4.40	4.50
e	0.65 BSC		
L	0.45	0.60	0.75
L1	1.00 REF		
$\theta$	0°		8°



SIDE VIEW



END VIEW

**Notes:**

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-153.

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<b>REFERENCE:</b>		
<b>DESCRIPTION:</b>	<b>TSSOP20, 4.4X6.5</b>	<b>PAGE 1 OF 2</b>

